

1:1 Active HDMI™ ReDriver™ with Optimized Equalization & I2C Buffer and RxTerm detection circuitry

Features

- → Supply voltage, VDD = $3.3V \pm 5\%$
- → Support for both DVI and HDMITM signals
- → Supports both AC-coupled and DC-coupled inputs
- → Supports DeepColorTM
- → High Performance, up to 2.5 Gbps per channel
- → 5V Tolerance on I²C path
- → Integrated 50-ohm (±10%) termination resistors at each high speed signal input
- → Integrated Rx termination detection circuit
- → Configurable output swing control (400mV, 500mV, 600mV, 750mV, 1000mV)
- → Configurable Pre-Emphasis levels (0dB, 1.5dB, 3.5dB, & 6.0dB, 9.0dB)
- → Configurable De-Emphasis (0dB, -3.5dB, -6.0dB, -9.5dB)
- → Optimized Equalization
- → Single default setting will support all cable lengths
- → 8kV Contact ESD protection on all input data/clock channels per IEC61000-4-2
- → Hot insertion support on output high speed pins & SCL/SDA pins only
- \rightarrow Propagation delay ≤ 1 ns
- → High Impedance Outputs when disabled
- → Packaging (Pb-free & Green): 42-contact TQFN (ZH42)

Description

Pericom Semiconductor's PI3HDMI101-B 1:1 active ReDriver™ circuit is targeted for high-resolution video networks that are based on DVI/HDMI™ standards and TMDS signal processing. The PI3HDMI101-B is an active ReDriver with Hi-Z outputs. The device receives differential signals from selected video components and drives the video display unit. This solution also provides a unique advanced pre-emphasis technique to increase rise and fall times which are reduced during transmission across long distances.

Each complete HDMI/DVI channel also has slower speed, side band signals, that are required to be switched. Pericom's solution provides a complete solution by integrating the side band buffer together with the high speed buffer in a single solution. Using Equalization at the input of each of the high speed channels, Pericom can successfully eliminate deterministic jitter caused by long cables from the source to the sink. The elimination of the deterministic jitter allows the user to use much longer cables (up to 25 meters).

The maximum DVI/HDMI Bandwidth of 2.5 Gbps provides 36-bit DeepColor™ support, which is offered by HDMI revision 1.3. The PI3HDMI101-B also provides enhanced robust ESD/EOS protection of 8kV, which is required by many consumer video networks today.

The Optimized Equalization provides the user a single optimal setting that can provide HDMI compliance for all cable lengths: 1 meter to 20 meters and color depths of 8bit/ch, or 12bit/ch.

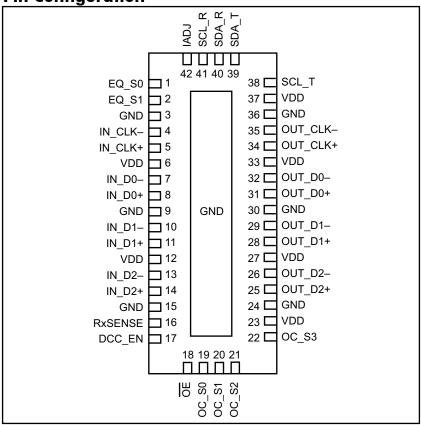
Pericom also offers the ability to fine tune the equalization settings in situations where cable length is known. For example, if 25 meter cable length is required, Pericom's solution can be adjusted to 16dB EQ to accept 25 meter cable length.

Using Pericom's patent-pending Rx termination detection circuit, PI3HDMI101-B can automatically disable its own input 50-Ohm termination when no 50-Ohm termination is detected in the HDMI Rx chipset. If a switch is used between the PI3HDMI101-B and the HDMI Rx, our part can detect the 50-Ohm termination in the switch to determine if our input should be off or on.

13-0005 1 PS8956B 03/06/13

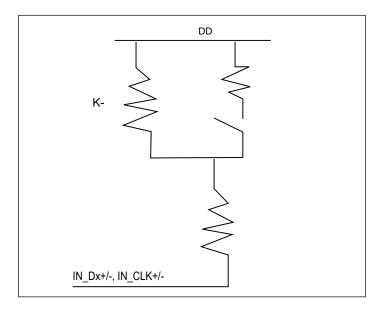


Pin Configuration



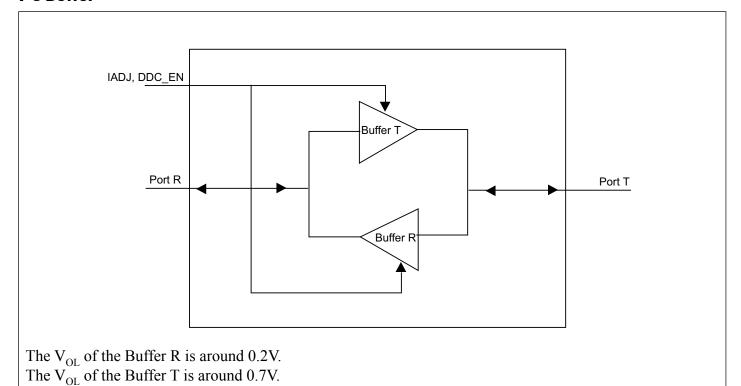
TMDS Receiver Block

Each high speed data and clock input has integrated equalization that can eliminate deterministic jitter caused by input cables. All activity can be configured using pin strapping. The Rx block is designed to receive all relevant signals directly from the HDMI™ connector without any additional circuitry, 3 High speed TMDS data, 1 pixel clock, and DDC signals. TMDS channels have the following termination scheme for Rx Sense support. The switching between 50-Ohm termination vs. 250K-Ohm termination is done automatically. The PI3HDMI101-B monitors the 50-Ohm termination in the Rx chipset behind our part, and when this 50-Ohm termination is not present, we disable our 50-Ohm termination at our input.





I²C Buffer



Functional Truth Tables

IADJ	External Pull-Up Range
Н	1K-Ohm to 2K-Ohm (HDMI spec)
L	> 3K-Ohm (4.7K-Ohm typically)

DDC_EN	Port T / Port R (if no external pull-up resistor					
L	Hi-Z (I ² C buffer disable)					
Н	(I ² C buffer enable)					

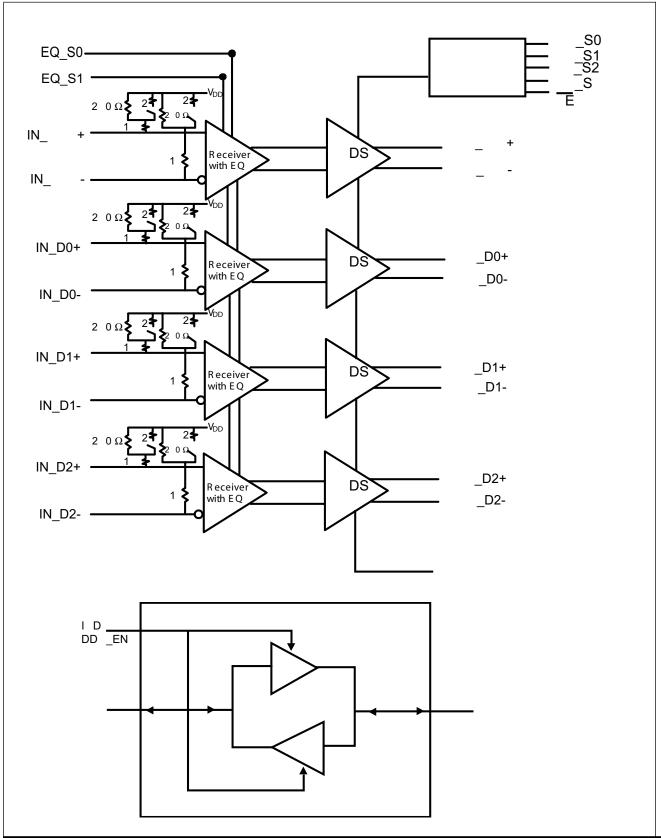


Pin Description

Pin #	Pin Name	I/O	Description	
5	IN_CLK+			
8	IN_D0+	т.	TMDC Positive impute	
11	IN_D1+	I	TMDS Positive inputs	
14	IN_D2+			
4	IN_CLK-			
7	IN_D0-	I	TMDS Negative inputs	
10	IN_D1-	1	TWD3 Negative inputs	
13	IN_D2-			
3, 9, 15, 24, 30, 36	GND	P	Ground	
18	ŌE	I	Output Enable, Active LOW	
41	SCL_R	I/O	DDC Clock , Source Side	
40	SDA_R	I/O	DDC Data, Source Side	
6, 12, 16, 23, 27, 33, 37	V _{DD}	P	3.3V Power Supply	
34	OUT_CLK+			
31	OUT_D0+		TMDC accition automate	
28	OUT_D1+	О	TMDS positive outputs	
25	OUT_D2+			
35	OUT_CLK-			
32	OUT_D0-	О	TMDS negative outputs	
29	OUT_D1-		TWD5 negative outputs	
26	OUT_D2-			
1	EQ_S0	I	Equalizer controls, both pins with internal pull-ups	
2	EQ_S1	1	Equalizer controls, both pins with internal pun-ups	
19	OC_S0			
20	OC_S1	I	Output buffer controls	
21	OC_S2	1	Note: All 4 pins have internal pull-ups	
22	OC_S3			
17	DDC_EN	I	I ² C path enable	
38	SCL_T	I/O	DDC Clock, Sink side	
39	SDA_T	I/O	DDC Data, Sink side	
42	IADJ	I	High/Low Voltage Selection, depends on I ² C external pull-up range	



Complete high speed input Rx block is as follows:(1)





Truth Table

ŌĒ	Function
0	Active
1	All TMDS outputs are Hi-Z

Truth Table 1

OC_S3 ⁽²⁾	OC_S2 ⁽²⁾	OC_S1 ⁽²⁾	OC_S0 ⁽²⁾	Vswing(mv)	Pre/de-emphasis
1	1	1	1	500	0dB
1	1	1	0	600	0dB
1	1	0	1	750	0dB
1	1	0	0	1000	0dB
1	0	1	1	500	0dB
1	0	1	0	500	1.5dB
1	0	0	1	500	3.5dB
1	0	0	0	500	6dB
0	1	1	1	400	0dB
0	1	1	0	400	3.5dB
0	1	0	1	400	6dB
0	1	0	0	400	9dB
0	0	1	1	1000	0dB
0	0	1	0	666	-3.5dB
0	0	0	1	500	-6dB
0	0	0	0	333	-9dB

EQ Setting Value Logic Table

EQ_S1 ⁽²⁾	EQ_S0 ⁽²⁾	Gain (dB)
1	1	Optimized Equalization (Default Setting)
1	0	8
0	1	3
0	0	15

Notes:

- 1. External pull-ups are required along SCL/SDA path
- 2. Internal 100K-Ohm pull-ups



Maximum Ratings

(Above which useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	65°C to +150°C
Supply Voltage to Ground Potential	0.5V to +4.0V
DC Input Voltage	0.5V to V _{DD}
DC Output Current	120mA
Power Dissipation	1.0W

Note:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Recommended Operating Conditions

Symbol	Parameter	Min.	Тур.	Max.	Units
V_{DD}	Supply Voltage	3.135	3.3	3.465	V
T _A	Operating free-air temperature	0		70	°C
TMDS Di	fferential Pins				
V_{ID}	Receiver peak-to-peak differential input voltage	150		1560	mVp-p
V _{IC}	Input common mode voltage	2		$V_{\rm DD} + 0.01$	V
V_{DD}	TMDS output termination voltage	3.135	3.3	3.465	V
R _T	Termination resistance	45	50	55	Ohm
	Signaling rate	0		2.5	Gbps
Control P	ins (OC_Sx, EQ_Sx, OE , DDC_EN)	·	·		·
V _{IH}	LVTTL High-level input voltage	2		V_{DD}	V
V _{IL}	LVTTL Low-level input voltage	GND		0.8	V
DDC Pins ((SCL_R, SCL_T, SDA_R, SDA_T)				
V _{I(DDC)}	Input voltage	GND		5.5	V
I ² C Pins (SCL_T, SDA_T)				
V _{IH}	High-level input voltage	0.7 x V _{DD}		5.5	V
$V_{\rm IL}$	Low-level input voltage	-0.5		0.3 x V _{DD}	V
V _{ICL}	Low-level input voltage contention (1)	-0.5		0.4	V
I ² C Pins (SO	CL_R, SDA_R)			•	•
V_{IH}	High-level input voltage	0.7 x V _{DD}		5.5	V
$V_{\rm IL}$	Low-level input voltage	-0.5		0.3 x V _{DD}	V

Notes:

^{1.} V_{IL} specification is for the first low level seen by the SCL/SDA lines. V_{ICL} is for the second and subsequent low levels seen by the SCL_T/SDA_T lines.



TMDS Compliance Test Results

Item	HDMI 1.3 Spec	Pericom Product Spec
Operating Conditions		
Termination Supply Voltage, V _{DD}	3.3V ≤ 5%	$3.30 \pm 5\%$
Terminal Resistance	50-Ohm ± 10%	45 to 55-Ohm
Source DC Characteristics at TP1		
Single-ended high level output voltage, VH	$V_{\mathrm{DD}} \pm 10 \mathrm{mV}$	V _{DD} ±10mV
Single-ended low level output voltage, VL	$(V_{DD} - 600 \text{mV}) \le \text{VL} \le (V_{DD} - 400 \text{mV})$	$(V_{DD} - 600 \text{mV}) \le VL \le (V_{DD} - 400 \text{mV})$
Single-ended output swing voltage, Vswing	400mV ≤ Vswing ≤ 600mV	400mV ≤ Vswing ≤ 600mV
Single-ended standby (off) output voltage, Voff	$V_{\mathrm{DD}} \pm 10 \mathrm{mV}$	$V_{DD} \pm 10 \text{mV}$
Transmitter AC Characteristics at TP1		
D: (* /E lle: /200/ 000/)	75ps ≤ Risetime/Falltime ≤ 0.4 Tbit	240
Risetime/Falltime (20%-80%)	(75ps ≤ tr/tf ≤ 242ps) @ 1.65 Gbps	240ps
Later Dein Classes & Transmitter Comments and	0.15 Tbit	(0,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,
Intra-Pair Skew at Transmitter Connector, max	(90.9ps @ 1.65 Gbps)	60ps max
	0.2 Tpixel	100
Inter-Pair Skew at Transmitter Connector, max	(1.2ns @ 1.65 Gbps)	100ps max
Cl. I ru	0.25 Tbit	02
Clock Jitter, max	(151.5ps @ 1.65 Gbps)	82ps max
Sink Operating DC Characteristics at TP2		
Input Differential Voltage Level, Vdiff	150 ≤ Vdiff ≤ 1200mV	$150 \text{mV} \le \text{V}_{\text{DIFF}} \le 1200 \text{mV}$
	$(V_{DD} - 300 \text{mV}) \le \text{Vicm} \le (V_{DD} - 37.5 \text{mV})$	$(V_{DD} - 300 \text{mV}) \le \text{Vicm} \le (V_{DD} - 37.5 \text{mV})$
Input Common Mode Voltage Level, V _{ICM}	Or	Or
	V _{DD} ±10%	V _{DD} ±10%
Sink DC Characteristics When Source Disa	abled or Disconnected at TP2	
Differential Voltage Level	$V_{\mathrm{DD}} \pm 10 \mathrm{mV}$	V _{DD} ±10mV
		1



1:1 Active HDMITM ReDriver™ with Optimized Equalization & I2C Buffer and RxTerm detection circuitry

Symbol	Parameter	Test Conditions	Min.	Typ.(1)	Max.	Units
I _{CC}	Supply Current	$V_{IH} = V_{DD}, V_{IL} = V_{DD} - 0.4V,$ $R_T = 50$ -Ohm, $V_{DD} = 3.3V$		120		mA
P_{D}	Power Dissipation	Data Inputs = 1.65 Gbps HDMI data pattern CLK Inputs = 165 MHz clock OC_Sx = Low, x = 0,1,2,3		400		mW
I_{CCQ}	Standby Current	\overline{OE} = HIGH, V_{DD} = 3.3V, RxSense = LOW		8		mA
TMDS Di	fferential Pins		,	·	1	
V _{OH}	Single-ended high-level output voltage		V _{DD} -		V _{DD} + 10	
V _{OL}	Single-ended low-level output voltage		V _{DD} - 600		V _{DD} - 400	mV 2x V _{swing}
V _{swing}	Single-ended output swing voltage	$V_{\mathrm{DD}} = 3.3 \mathrm{V}, R_{\mathrm{T}} = 50\text{-Ohm}$ Pre-emphasis/De-emphasis = 0dB	400		600	
V _{OD(O)}	Overshoot of output differential voltage			6%	15%	
V _{OD(U)}	Undershoot of output differential voltage			12%	25%	
$\Delta V_{OC(SS)}$	Change in steady-state common-mode output voltage between logic states			0.5	5	mV
I _(OS)	Short circuit output current				12	mA
V _{ODE(SS)}	Steady state output differential voltage	OC_Sx = GND, Data Inputs = 250	560		840	
V _{ODE(PP)}	Peak-to-peak output differential voltage	Mbps HDMI data pattern, 25 MHz pixel clock	800		1200	mVp-p
V _{I(open)}	Single-ended input voltage under high impedance input or open input	$I_I = 10 \mu A$	V _{DD} -		V _{DD} + 10	mV
R _{INT}	Input termination resistance	$V_{\rm IN} = 2.9 V$	45	50	55	ohm
Control P	ins (OE, DDC_EN, IADJ)					
I _{IH}	High-level digital input current	$V_{IH} = 2V \text{ or } V_{DD}$	-10		10	μΑ
I_{IL}	Low-level digital input current	V _I = GND or 0.8 V	-10		10	μΑ
I ² C Pins (SO	CL_T, SDA_T) (T Port)		•	•	•	
τ.,	Input leake go gurrant	V _I = 5.5 V	-50		50	
I _{ikg}	Input leakage current	$V_{I} = V_{DD}$	-20		20	μΑ
I _{OH}	High-level output current	$V_{O} = 3.6 \text{ V}$	-10		10	μΑ
$ m I_{IL}$	Low-level input current	$V_{IL} = GND$	-40		40	μΑ
V_{OL}	Low-level output voltage	$I_{OL} = 2.5 \text{ mA}$ $IADJ = H$	0.65		0.9	V

(Table Continued)



Electrical Characteristics (Cont..)

Symbol	Parameter	Test Conditions	Min.	Typ. ⁽¹⁾	Max.	Units	
C _{IO}	Input/output capacitance	$V_I = 5.0 \text{ V} \text{ or } 0 \text{ V}, \text{Freq} = 100 \text{kHz}$			25	Г	
		$V_I = 3.0 \text{ V}$ or 0 V, Freq = 100kHz			10	pF	
V _{OH(TTL)} ¹	TTL High-level output voltage	$I_{OH} = -8 \text{ mA}$	2.4			V	
V _{OL(TTL)} ¹	TTL Low-level output voltage	$I_{OL} = 8 \text{ mA}$			0.4	V	

Note:

^{1.} Voh/Vol of external driver at the R and T ports.

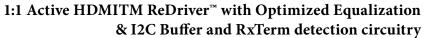
I ² C Pins (SCL_R, SDA_R) (R Port)						
I _{ikg}	Imput looks as assument	$V_{\rm I} = 5.5 \ { m V}$	-50	50		
	Input leakage current	$V_{I} = V_{DD}$	-20	20	μΑ	
I _{OH}	High-level output current	$V_O = 3.6 \text{ V}$	-10	10	μΑ	
I _{IL}	Low-level input current	$V_{IL} = GND$	-10	10	μΑ	
V _{OL}	Low-level output voltage	$I_{OL} = 4 \text{ mA}, I_{ADJ} = H$		0.2	V	
C _I	Tunnet annualitan	V _I = 5.0 V or 0 V, Freq = 100kHz		25	Г	
	Input capacitance	$V_I = 3.0 \text{ V} \text{ or } 0 \text{ V}, \text{Freq} = 100 \text{kHz}$		10	pF	

Switching Characteristics (over recommended operating conditions unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ. (1)	Max.	Units	
TMDS Differential Pins							
tpd	Propagation delay				2000		
t _r	Differential output signal rise time (20% - 80%)	$V_{DD} = 3.3V$, $R_T = 50$ -Ohm, pre-emphasis/de-emphasis = 0dB	75		240		
t _f	Differential output signal fall time (20% - 80%)		75		240		
t _{sk(p)}	Pulse skew			10	50		
t _{sk(D)}	Intra-pair differential skew			23	50		
t _{sk(o)}	Inter-pair differential skew ⁽²⁾				100	ps	
t _{jit(pp)}	Peak-to-peak output jitter from TMDS clock channel	pre-emphasis/de-emphasis = 0dB, Data Inputs = 1.65 Gbps HDMI data		15	30		
t _{jit(pp)}	Peak-to-peak output jitter from TMDS data channel	pattern CLK input = 165 MHz clock		18	50		
t _{DE}	De-emphasis duration	de-emphasis = -3.5dB, Data Inputs = 250 Mbps HDMI data pattern, CLK output = 25 MHz clock		240			

10

(Table Continued)





Switching Characteristics (Cont..)

Symbol	Parameter	Test Conditions	Min.	Typ. (1)	Max.	Units
t_{SX}	Select to switch output				10	
t _{en}	Enable time				200	ns
t _{dis}	Disable time				10	1
I ² C PINS	(SCL_R, SDA_R, SCL_T, SDA_T)					
t _{PLH}	Propagation delay time, low-to-high-level output SCL_T/SDA_T to SCL_R/SDA_R	$IADJ = V_{DD}$ $C_{LOAD} = 300 \text{ pF}$			500	
$t_{ m PHL}$	Propagation delay time, high-to-low-level output SCL_T/SDA_T to SCL_R/SDA_R	Tbuffer: Rpu = 2K, Vpu = 3.0V			136	-
t _{PLH}	Propagation delay time, low-to-high-level output SCL_T/SDA_T to SCL_R/SDA_R	Rbuffer: Rpu = 1.2K, Vpu = 3.3V or			450	
$t_{ m PHL}$	Propagation delay time, high-to-low-level output SCL_T/SDA_T to SCL_R/SDA_R	$Rpu = 1.8K, Vpu = 5V$ $IADJ = GND$ $C_{LOAD} = 100 pF$			136	ns
t _r	SCL_T/SDA_T Output signal rise time				999	
t_{f}	SCL_T/SDA_T Output signal fall time	Sac Fig. A			90	
t _r	SCL_R/SDA_R Output signal rise time	See Fig. A			999	
t_{f}	SCL_R/SDA_R Output signal fall time				90]



Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
t _{set}	Enable to start condition			6	10	
t _{hold}	Enable after stop condition			6	10	ns

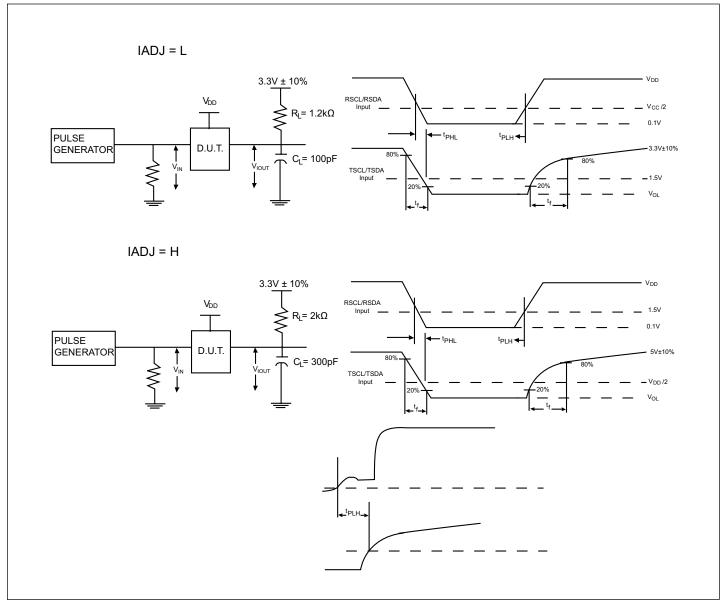


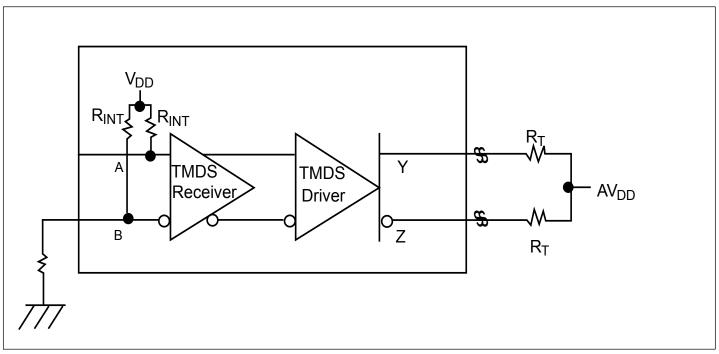
Figure A. I²C Timing Test Circuit and Definition

13-0005



TMDS output oscillation elimination

The TMDS inputs do not incorporate a squelch circuit. Therefore, we recommend the input to be externally biased to prevent output oscillation. One pin will be pulled high to VDD with the other grounded through a 1.5K-Ohm resistor as shown.



TMDS Input Fail-Safe Recommendation



Recommended Power Supply Decoupling Circuit

Figure 1 is the recommended power supply decoupling circuit configuration. It is recommended to put 0.1μF decoupling capacitors on each VDD pins of our part, there are four 0.1µF decoupling capacitors are put in Figure 1 with an assumption of only four VDD pins on our part, if there is more or less VDD pins on our Pericom parts, the number of 0.1µF decoupling capacitors should be adjusted according to the actual number of VDD pins. On top of 0.1µF decoupling capacitors on each VDD pins, it is recommended to put a 10μF decoupling capacitor near our part's VDD, it is for stabilizing the power supply for our part. Ferrite bead is also recommended for isolating the power supply for our part and other power supplies in other parts of the circuit. But, it is optional and depends on the power supply conditions of other circuits.

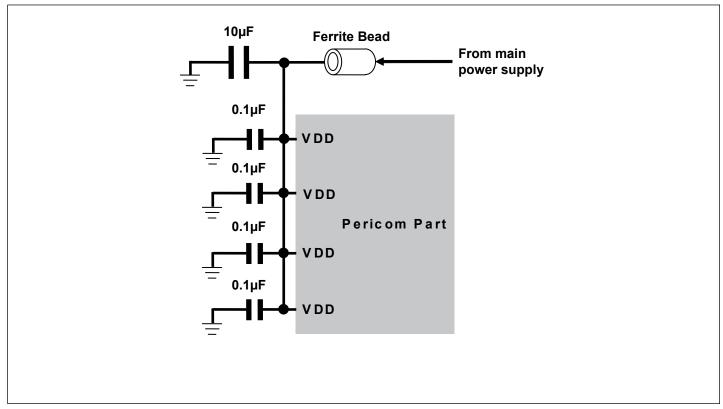


Figure 1 Recommended Power Supply Decoupling Circuit Diagram



Requirements on the Decoupling Capacitors

There is no special requirement on the material of the capacitors. Ceramic capacitors are generally being used with typically materials of X5R or X7R.

Layout and Decoupling CapacitorPlacement Consideration

- i. Each $0.1\mu F$ decoupling capacitor should be placed as close as possible to each V_{DD} pin.
- ii. V_{DD} and GND planes should be used to provide a low impedance path for power and ground.
- iii. Via holes should be placed to connect to V_{DD} and GND planes directly.
- iv. Trace should be as wide as possible
- Trace should be as short as possible.
- vi. The placement of decoupling capacitor and the way of routing trace should consider the power flowing criteria.
- vii. 10μF capacitor should also be placed closed to our part and should be placed in the middle location of 0.1μF capacitors.
- viii. Avoid the large current circuit placed close to our part; especially when it is shared the same V_{DD} and GND planes. Since large current flowing on our V_{DD} or GND planes will generate a potential variation on the V_{DD} or GND of our part.

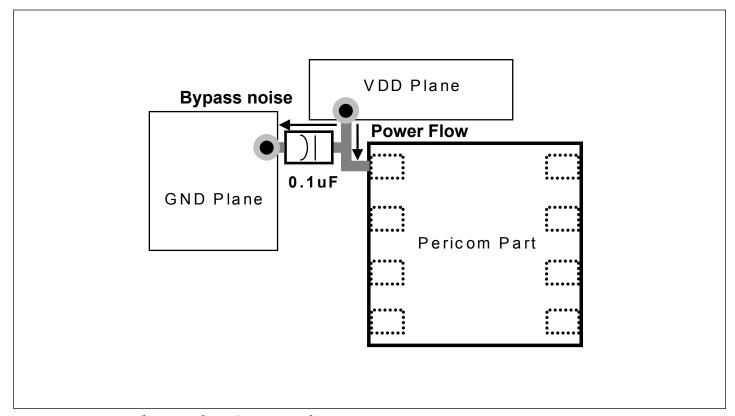


Figure 2 Layout and Decoupling Capacitor Placement Diagram



Application Information

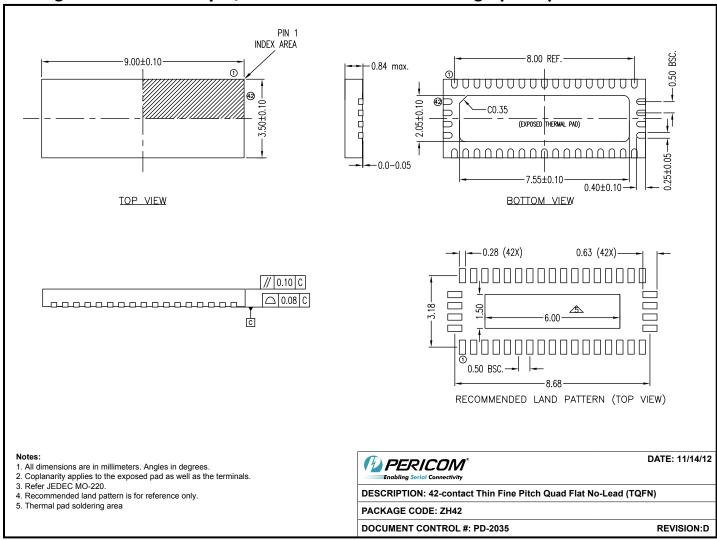
Supply Voltage

All V_{DD} pins are recommended to have a $0.01\mu F$ capacitor tied from V_{DD} to GND to filter supply noise

TMDS inputs

Standard TMDS terminations have already been integrated into Pericom's PI3HDM101-A device. Therefore, external terminations are not required. Any unused port must be left floating and not tied to GND.

Package Mechanical: 42-pin, Low Profile Quad Flat Package (ZH42)



Ordering Information

Ordering Code	Package Code	Package Description
PI3HDMI101-BZHE	ZH	42-pin, Pb-free & Green TQFN

Notes:

- Thermal characteristics can be found on the company web site at www.pericom.com/packaging/
- E = Pb-free and Green
- Adding an X Suffix = Tape/Reel
- HDMI & DeepColor are trademarks of Silicon Image

Pericom Semiconductor Corporation • 1-800-435-2336 • www.pericom.com 16